

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Shigeki Satou et al.
Application No. : 10/582,994
Filed : June 14, 2006
For : DIELECTRIC PASTE FOR SPACER LAYER OF A MULTI-
LAYERED CERAMIC ELECTRONIC COMPONENT
Examiner : Khanh Tuan Nguyen
Art Unit : 1796
Docket No. : 890050.543USPC
Date : July 22, 2008

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT TRANSMITTAL

Commissioner for Patents:

In accordance with 37 CFR 1.56 and 1.97 through 1.98, applicants wish to make known to the U.S. Patent and Trademark Office the references set forth on the attached Information Disclosure Statement. Copies of cited U.S. patents and published patent applications are not required and accordingly have not been provided. Copies of any other cited references are enclosed. As to any reference cited, applicants do not admit that it is “prior art” under 35 U.S.C. §§ 102 or 103, and specifically reserve the right to traverse or antedate any such reference, as by a showing under 37 CFR 1.131 or other method. Although the aforesaid references are made known to the Patent and Trademark Office in compliance with applicants’ duty to disclose all information they are aware of which is believed relevant to the examination of the above-identified application, applicants believe that their invention is patentable.

Please acknowledge receipt of this Information Disclosure Statement and kindly make the cited references of record in the above-identified application.

A fee of \$180 is submitted in accordance with 37 CFR 1.97(c). The Director is authorized to charge any other fees which may be required, or credit any overpayment to Deposit Account No. 19-1090.

Respectfully submitted,

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Enclosures:

Information Disclosure Statement

Cited References (7)

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